

**MDR741F**

2.45GHz BPF for Wireless LAN & Bluetooth

**Characteristics**

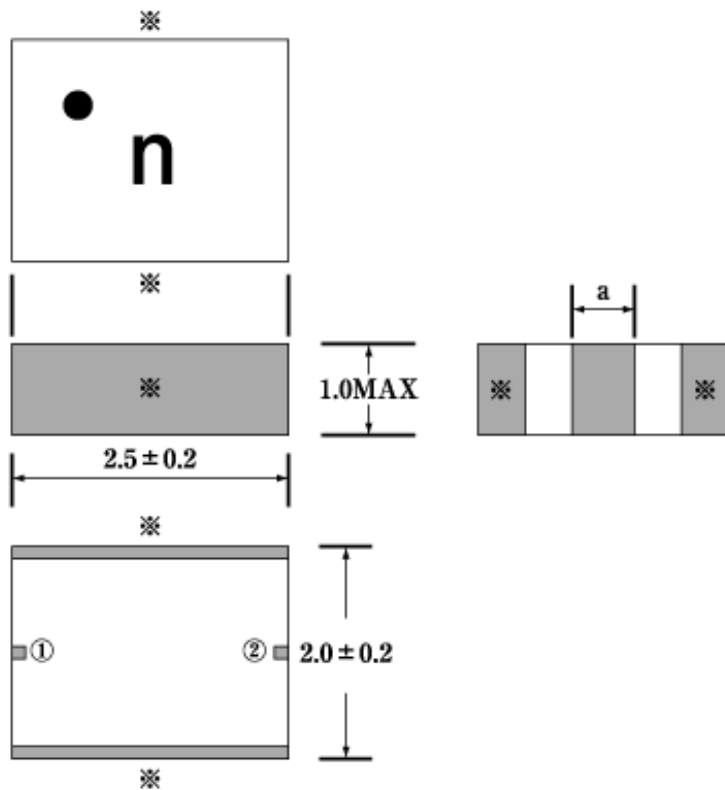
<b>MDR741F</b>	
Zin/Zout	50 ohm Nominal
Fc	2450MHz Nominal
Pass Band	2400-2500MHz
Insertion Loss	1.7 dB max (2400-2500MHz at 25 Deg.C)
	2.0 dB max (2400-2500MHz at -40 up to +85 Deg.C)
Ripple	0.8 dB max (2400-2500MHz)
V.S.W.R	2.0 max (2400-2500MHz)
Attenuation	25 dB min (at 1750MHz)
	25 dB min (at 2100MHz)
	22 dB min (at 4800-5000MHz)

**Number of ordered pieces**

2000pcs/Reel

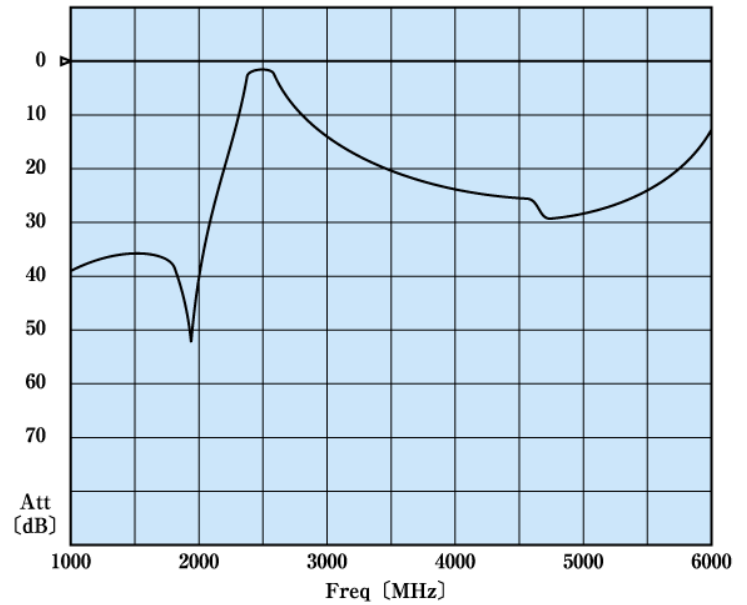
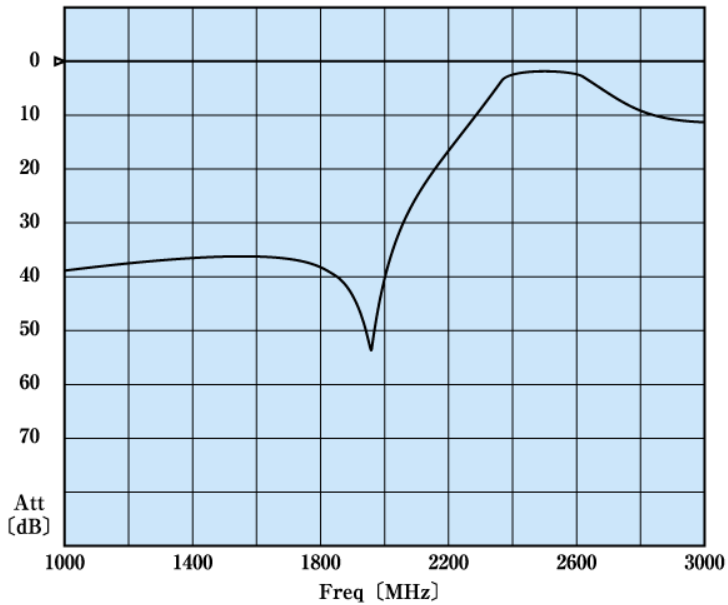
**Dimensions**

Dimension (Unit : mm)



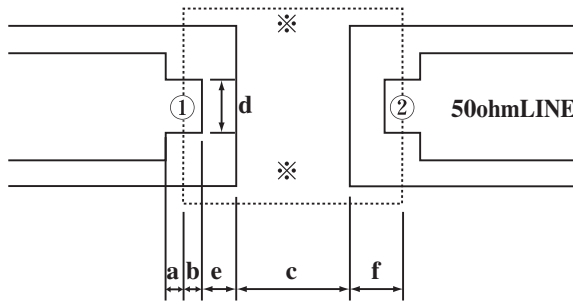
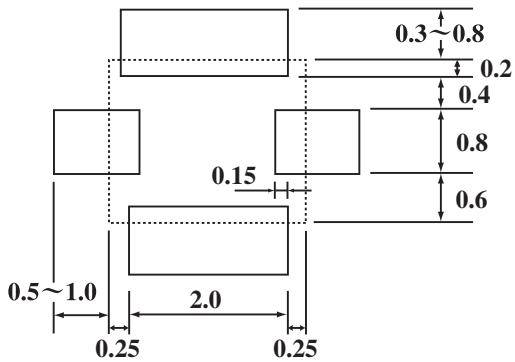
Terminal	
①	Input
②	Output
※	GND

$a=0.5 \pm 0.2$



Resist pattern

Land pattern

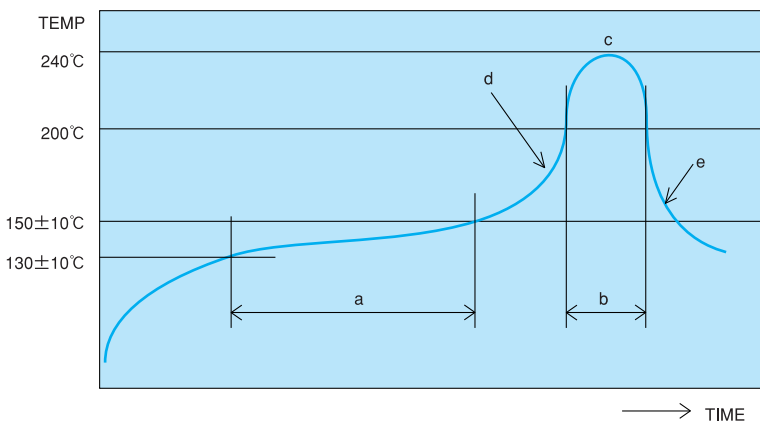


Terminal	
①	Input
②	Output
※	GND

Example : t=1.0mm  
 Glass-epoxy board  
 Glass-fluorine board  
 (High Frequency)

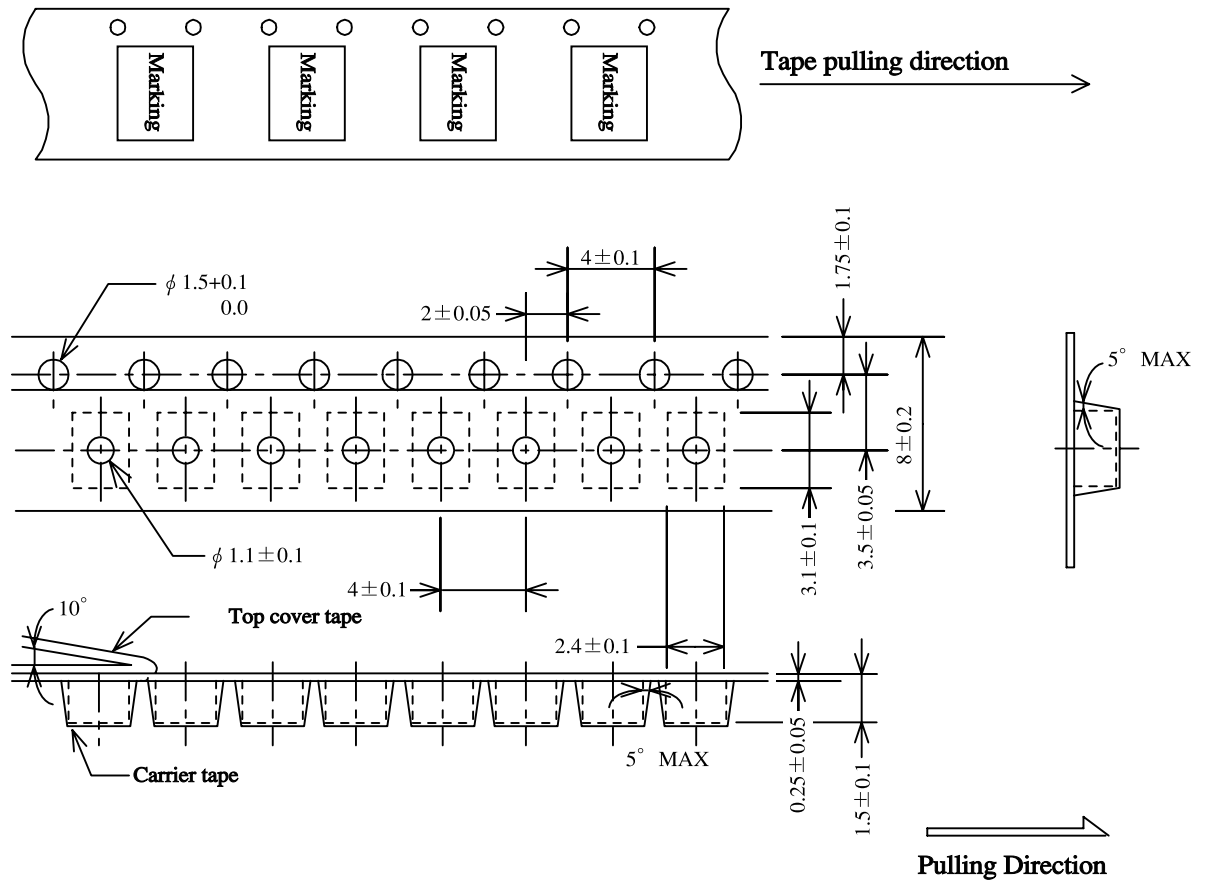
a=0.2  
 b=0.2  
 c=1.3  
 d=0.6  
 e=0.4  
 f=0.6  
 (Unit : mm)

Reflow-soldering conditions(For reference)

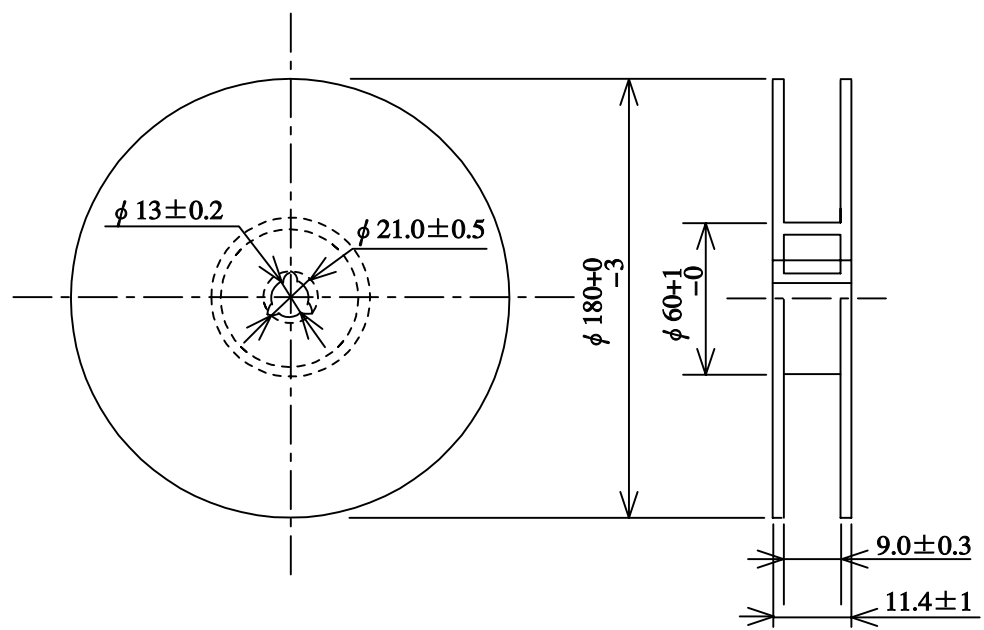


High temperature reflow-soldering conditions  
 (No more than 2 flows allowed)  
 a:Preheating 40 to 120 seconds  
 b:Heating 50 seconds  
 c:Peak temperature 240°C,max.  
 d:Temperature rising slope 10°C/1 second,max.  
 e:Temperature falling slope 8°C/1 second,max.

**Taping Dimensions (Unit:mm)**



**Reel Dimensions (Unit:mm)**



(2,000pcs/reel)